

Board Level Cooling – Space Saving 5425

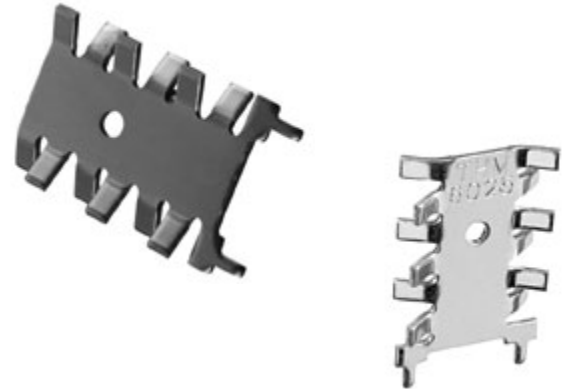


BOARD LEVEL COOLING – Space Saving 5425

Space Saving 5425 is a series of staggered fin board level heat sinks designed to cool TO-220 and TO-220-single gauge devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
542502B00000G	TO-220, TO-220-single gauge
542502D00000G	TO-220, TO-220-single gauge
6025DG	TO-220, TO-220-single gauge (0.020")
6025B-TTG	TO-220, TO-220-single gauge (0.020")



HEAT SINK DETAILS

Property	Details
Material	See Table Below
Finish	See Table Below
Device Attachment Options	Requires Mounting Kit
Thermal Interface Material	-

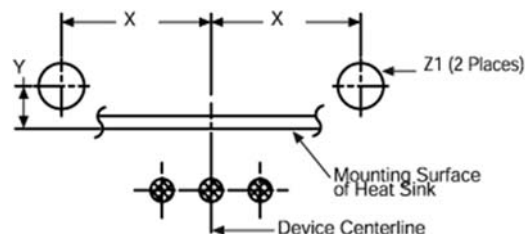
Property	Details
Heat Sink Width (mm)	22.22
Heat Sink Length (mm)	6.35
Heat Sink Height (mm)	31.75
Heat Sink Mounting Direction	Vertical

MECHANICAL & PERFORMANCE

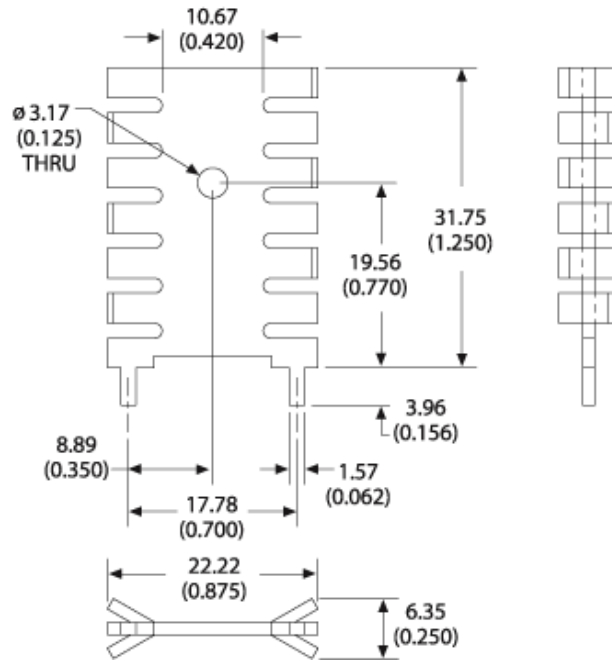
Drawing dimensions are shown in mm, (in)

Part Number	Material	Finish	"X" Dim	"Y" Dim	"Z" Dim
542502B00000G	Aluminum	Black	8.89 (0.350)	0.64 (0.025)	2.39 (0.094)
542502D00000G	Aluminum	Tin Plated	8.89 (0.350)	0.64 (0.025)	2.39 (0.094)
6025DG	Copper	Tin Plated	8.89 (0.350)	0.64 (0.025)	2.54 (0.100)
6025B-TTG	Copper	Black Paint	8.89 (0.350)	0.50 (0.020)	2.36 (0.093)

Mounting Details:

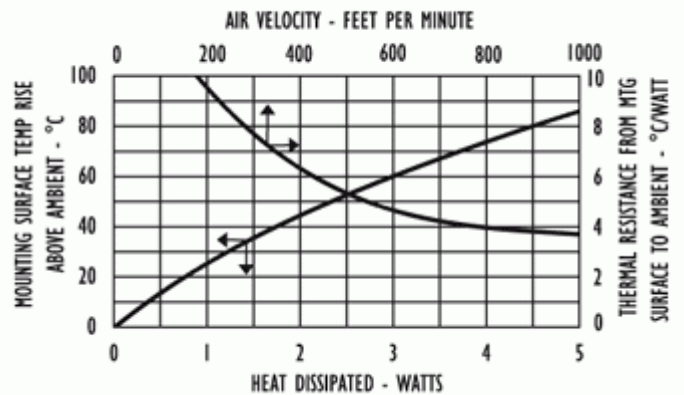
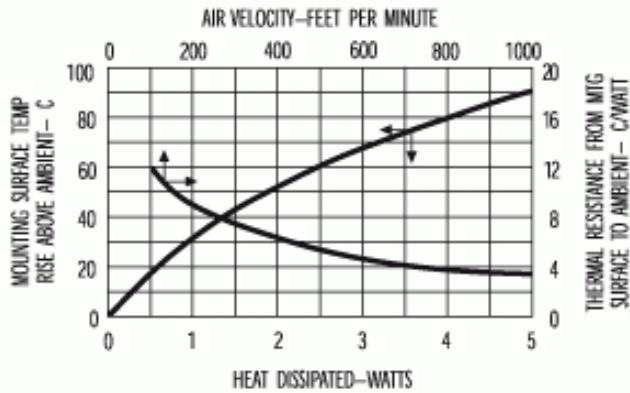


Board Level Cooling – Space Saving 5425



Part Number: 542502B00000G and 542502D00000G

Part Number: 6025DG and 6025B-TTG



USA: 1.855.322.2843
EUROPE: 39.051.764002
ASIA: 86.21.6115.2000 x8122